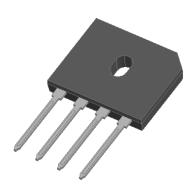
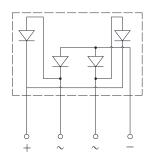




Low VF Bridge Rectifiers





Features

- UL recognition, file #E230084
- Glass passivated chip junction
- Ideal for printed circuit boards
- High surge current capability
- Low VF
- Solder dip 275 °C max. 7 s, per JESD 22-B106

Typical Applications

General purpose use in AC/DC bridge full wave rectification for switching power supply, home appliances, office equipment, industrial automation applications.

Mechanical Data

• Package: GBU

Molding compound meets UL 94 V-0 flammability

rating, RoHS-compliant

• Terminals: Tin plated leads, solderable per

J-STD-002 and JESD22-B102

• Polarity: As marked on body

■Maximum Ratings (Ta=25°C Unless otherwise specified)

■ IMAXIII UIII Ratiiigs (1a-23 € Oliiess otilei wise specified)						
PARAMETER		SYMBOL	UNIT	GBUL2508		
Device marking code				GBUL2508		
Maximum Repetitive Peak Reverse Voltage		VRRM	V	800		
Maximum RMS Voltage		VRMS	V	560		
Maximum DC blocking Voltage		VDC	V	800		
Average rectified output current @60Hz sine wave, R-load	With heatsink Tc =125°C	lo	А	25.0		
	Without heatsink Ta =25°C			4.0		
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25°C		· IFSM	А	450		
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C				900		
Current squared time @1ms≤t≤8.3ms Tj=25°C, Rating of per diode		l²t	A ² S	840		
Storage temperature		T _{stg}	°C	-55 ~ + 150		
Junction temperature		Тј	°C	-55 ~ +150		
Dielectric strength @ terminals to case, AC 1 minute		V _{dis}	KV	2.5		
Mounting torque @recommend torque: 5kg·cm		T _{or}	kg⋅cm	8.0		

GBUL2508

■Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	Min	Тур	Max
Instantaneous forward voltage drop per diode	VF	V	IFM=12.5A	0.80	0.90	0.92
DC reverse current at rated DC blocking voltage per diode	IR	μА	T _j =25℃	-	0.16	5
	ıĸ.		T _j =125°C	-	55	100
Junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	85	170	350

■Thermal Characteristics $(T_a=25$ $^{\circ}$ C Unless otherwise specified)

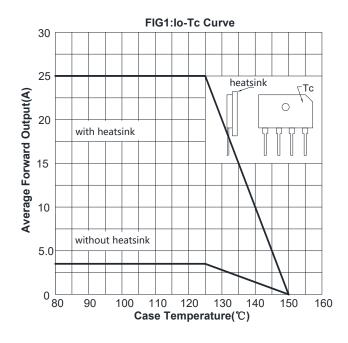
PARAMETER		SYMBOL	UNIT	GBUL2508
	Between junction and ambient, Without heatsink	R ₀ J-A		25.0
Thermal Resistance	Between junction and Lead, With heatsink	R ₀ J-L	°C/W	3.0
	Between junction and Case, With heatsink	RөJ-С		0.5

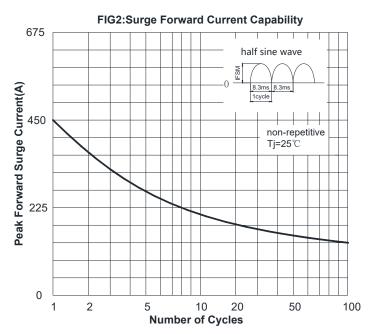
Note: Device mounted on 75mm x 45mm x 5.5mm Aluminum Plate Heatsink.

■Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
GBUL2508	B1	Approximate 3.96	20	1000	2000	TUBE

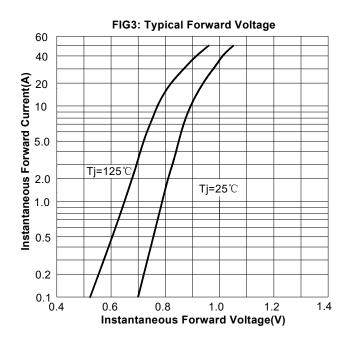
■ Characteristics(Typical)

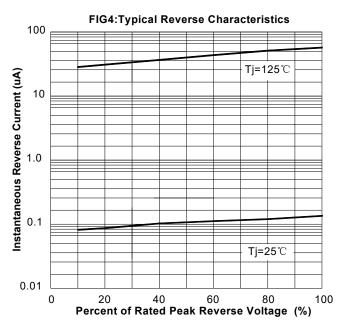




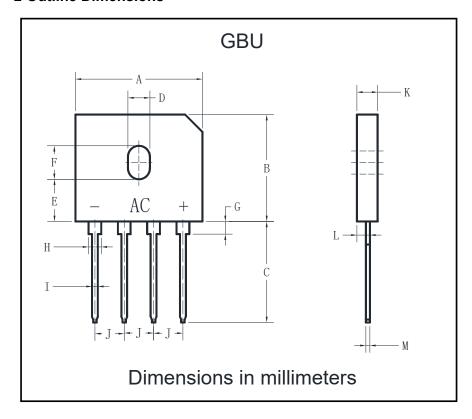








■ Outline Dimensions



GBU					
Dim	Min	Max			
Α	21.80	22.30			
В	18.30	18.80			
С	17.50	18.00			
D	3.30	3.90			
E	7.10	7.50			
F	5.50	5.90			
G	1.91	2.54			
Н	2.06	2.54			
I	1.02	1.27			
J	4.83	5.33			
K	3.30	3.56			
L	2.40	2.66			
М	0.46	0.56			



GBUL2508

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